

## **SPECIFICATION**

**MODEL: GL-5730WEA-2**



- **1. Features**
- **2. Applications**
- **3. Product Naming**
- **4. External Dimensions**
- **5. The main optical and electrical properties**
- **6. Absolute Maximum Rating**
- **7. Spectrum Distribution**
- **8. Reliability Test Standards**
- **9. White color coordinates map**
- **10. Solder conditions**



■ **1. Features**

- 1.1 Package: 5.7\*3.0\*0.9mm
- 1.2 Emitted Color: White
- 1.3 Mono-color type
- 1.4 Soldering methods: All SMT assembly methods
- 1.5 Comply RoHS standard

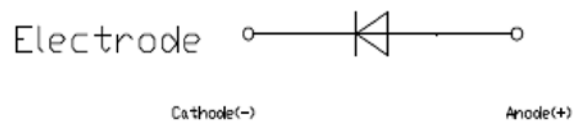
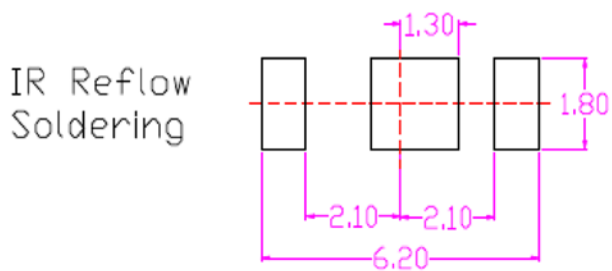
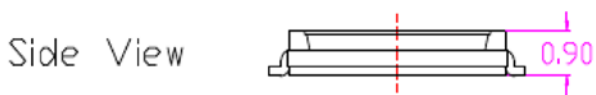
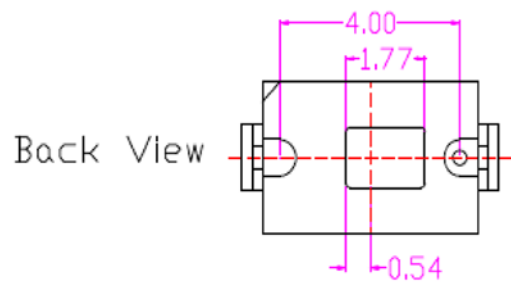
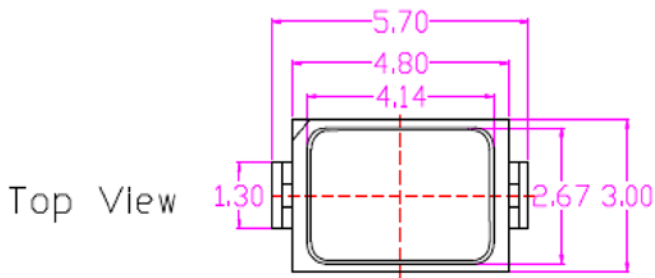
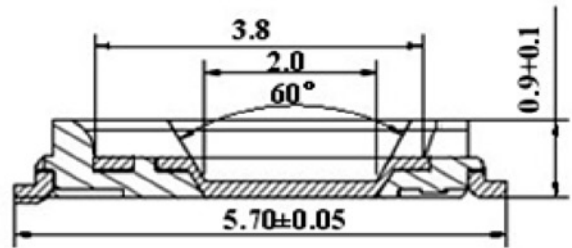
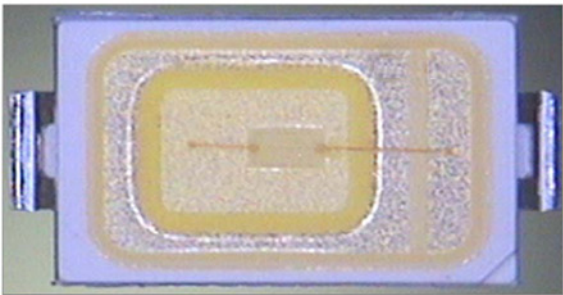
■ **2. Applications**

Apply to indoor lighting, outdoor lighting field

■ **3. Product Naming**

<b>GL</b>	<b>5730</b>	<b>W</b>	<b>X</b>	<b>X</b>	<b>—</b>	<b>X</b>
Company Name: Good Led	products model: 5730	LED Color Products: White	Chip manufacturers E-EPISTAR	Chip code: A+:(20*40) A:(20*38) B:(17*34)		Angle: 1:(140°C) 2:(120°C)

4. External Dimensions



■ **5. The main optical and electrical properties (Ta=25°C)**

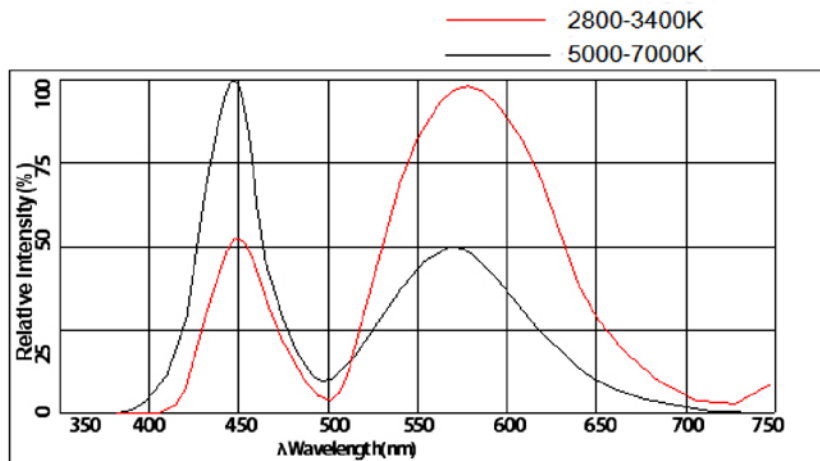
Project	Symbol	Conditions	Minimum	Average	Max.	Units
Forward Voltage	VF	IF=150mA	3	3,2	3,4	V
Reverse current	IR	VR=1.2V			5	μA
Flux	Φ	IF=150mA	50		60	Lm
Color Temperature	CCT	IF=150mA	2800		7000	K
Color Rendering Index	Ra	IF=150mA	60		85	

■ **6. Absolute Maximum Rating (Ta=25°C)**

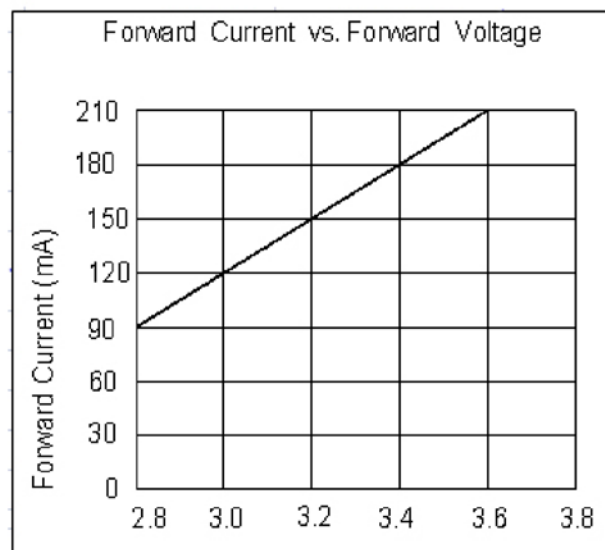
Project	Symbol	Limit parameter	Units
Forward Current	IF	150	mA
Recommended Current	IF	≤120	mA
Pulse peak current	IFP	500	mA
Reverse Voltage	VR	5	V
Power	PD	0,5	W
Operating temperature	Topr	(-30~+85)	°C
Storage Temperature	Tstg	(-40~+100)	°C
Soldering temperature	Tsol	reflow soldering: 250°C/10(Seconds0); Hand soldering: 300°C/3(Seconds)	
ESD Sensitivity	ESD	2000V HBM	

- 7. Typical electro-optical characteristics curves

**Spectrum Distribution TA=25°C**

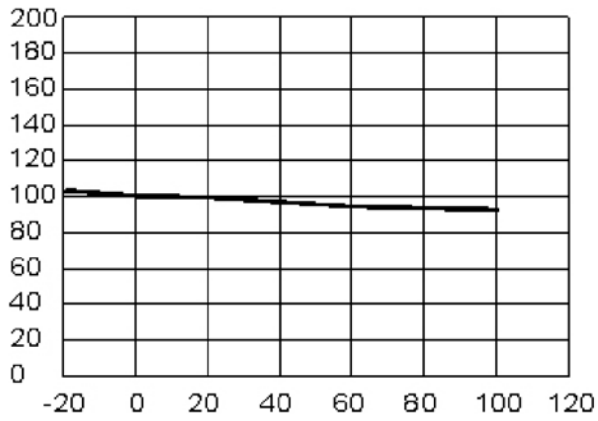


**Forward voltage and forward current curves TA=25°C**



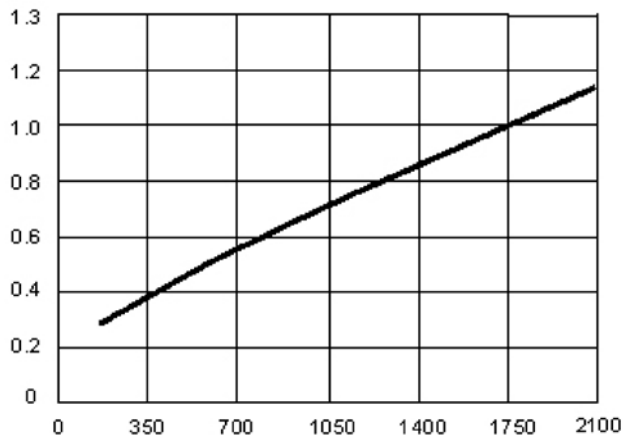


Relative Luminous Intensity (%)

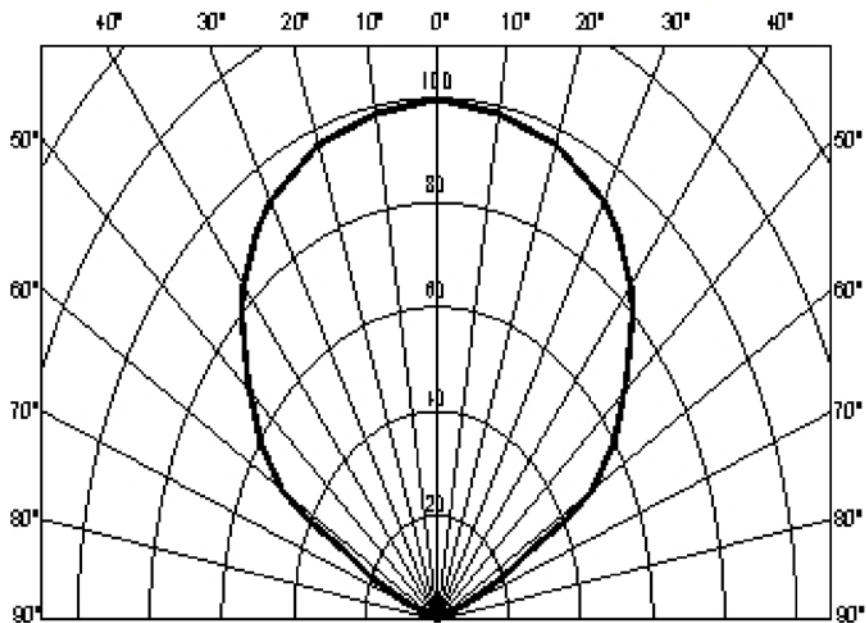


Ambient Temperature Ta (°C)

Normalized Relative Luminous Flux



Forward Current (mA)

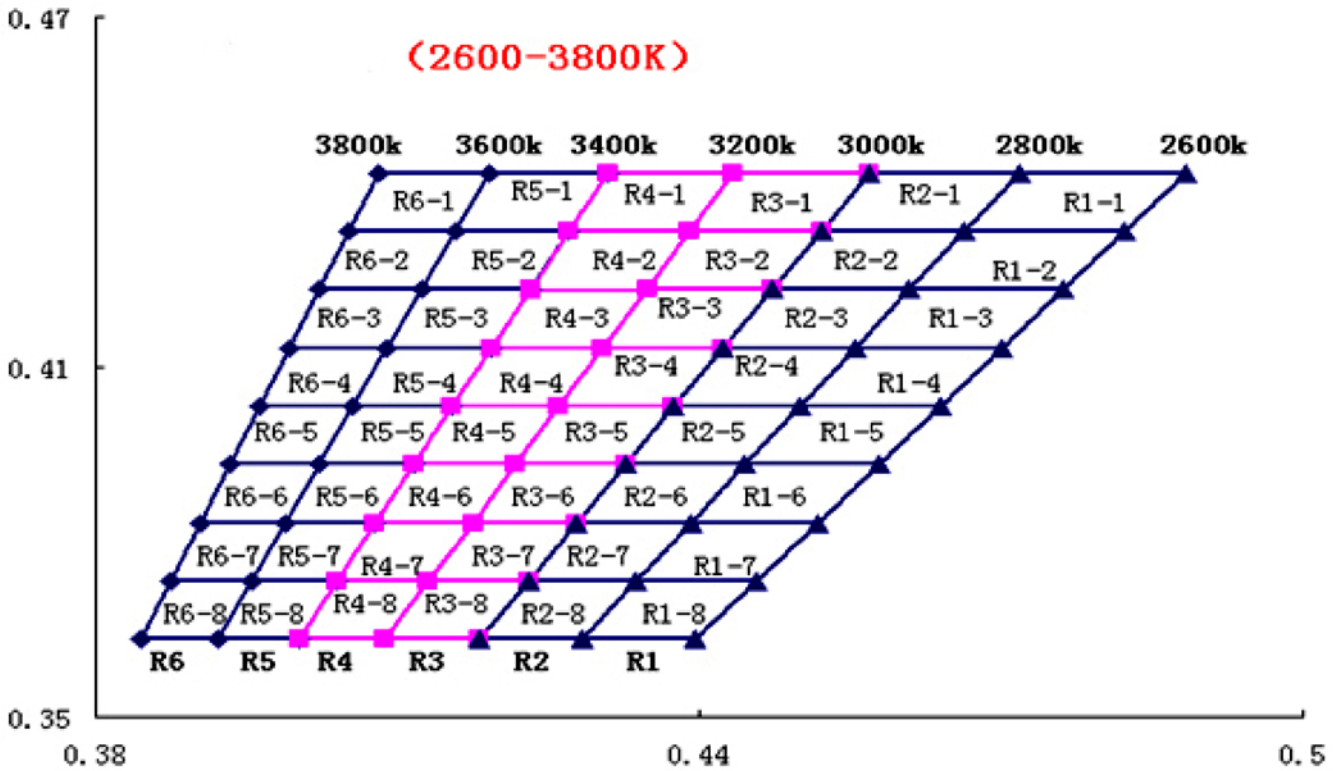


## 8. Reliability Test Standards

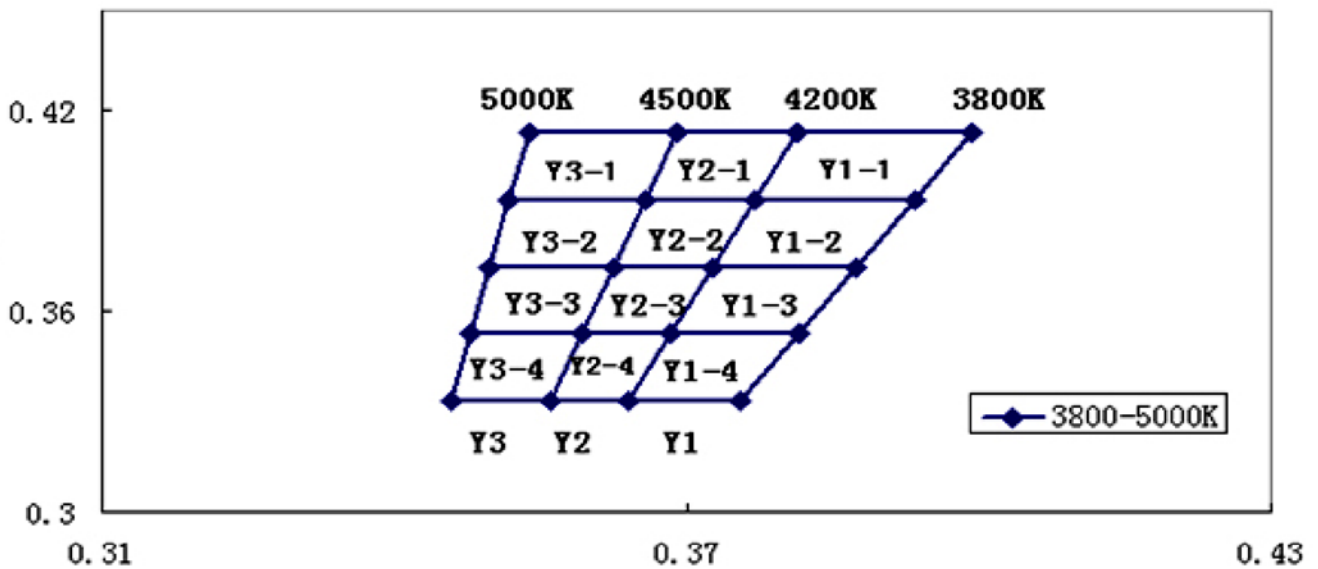
Type	Pilot project	Test conditions	Duration	The number of samples	Charge level
Environmental testing	Temperature cycling	45°C(30Min)~25°C(5Min) ~100°C(30Min)~25°C(5Min)	Cycle 100 Round	30	0/30
	Thermal Shock	-40°C(15Min) ~100°C(15Min)	Cycle 300 Round	30	0/30
	Humidity cycle	30°C~65°C RH=90% 24H/1Round	Cycle 50 Round	30	0/30
	High Temperature Storage	T <sub>a</sub> =100°C	1000H	30	0/30
	Cryogenic storage	T <sub>a</sub> =-40°C	1000H	30	0/30
	High temperature and humidity storage	T <sub>a</sub> =60°C RH=90%	1000H	30	0/30
Life test	Life test at room temperature	T <sub>a</sub> =25°C IF=150mA	1000H	30	0/30
	High temperature and humidity life test	T <sub>a</sub> =60°C RH=90% IF=150mA	1000H	30	0/30
	Low-temperature life test	T <sub>a</sub> =-30°C IF=150mA	1000H	30	0/30
Destructive test	Resistance to soldering heat	T <sub>sol</sub> =360°C±5°C,10S	Welding time	5	0/5
	Solderability	T <sub>sol</sub> =350°C±5°C,5S Using flux	Welding time	5	0/5
Mechanical test	Vibration test	20G 20-2000HZ 4Min X, Y, Z	Loop 4 times in each direction	5	0/5
	Drop test	75mm	Cycle 3 Round	5	0/5



## 9. White color coordinates map

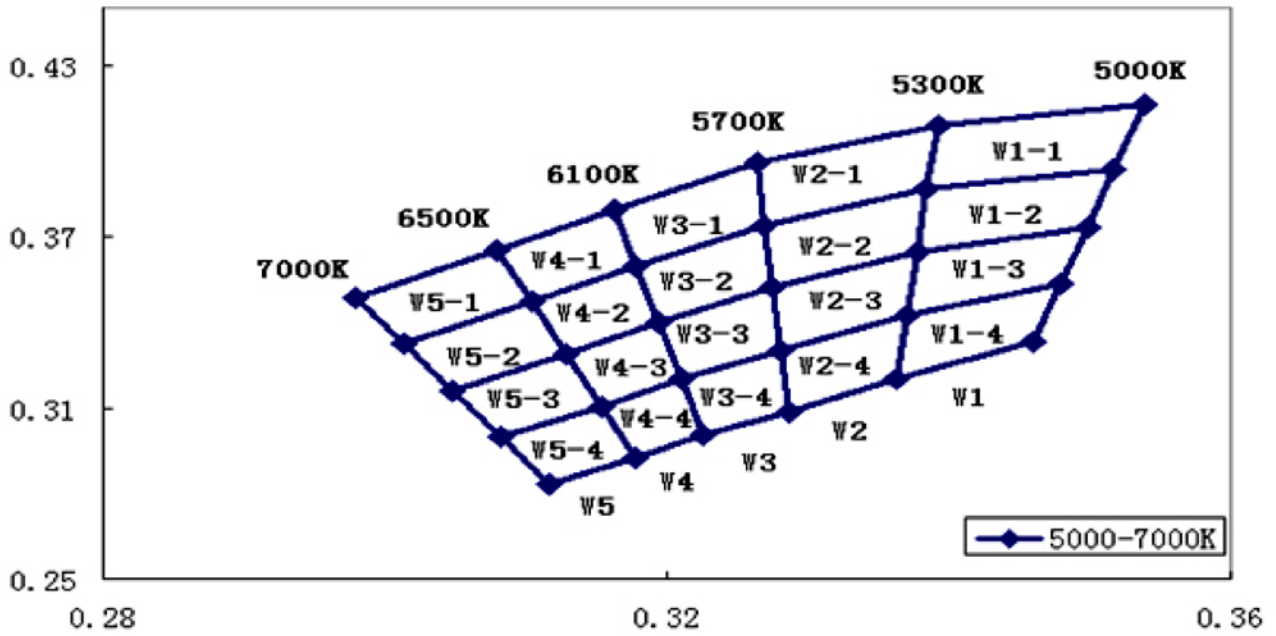


## 3800-5000K





**5000-7000K**



10. Solder conditions

